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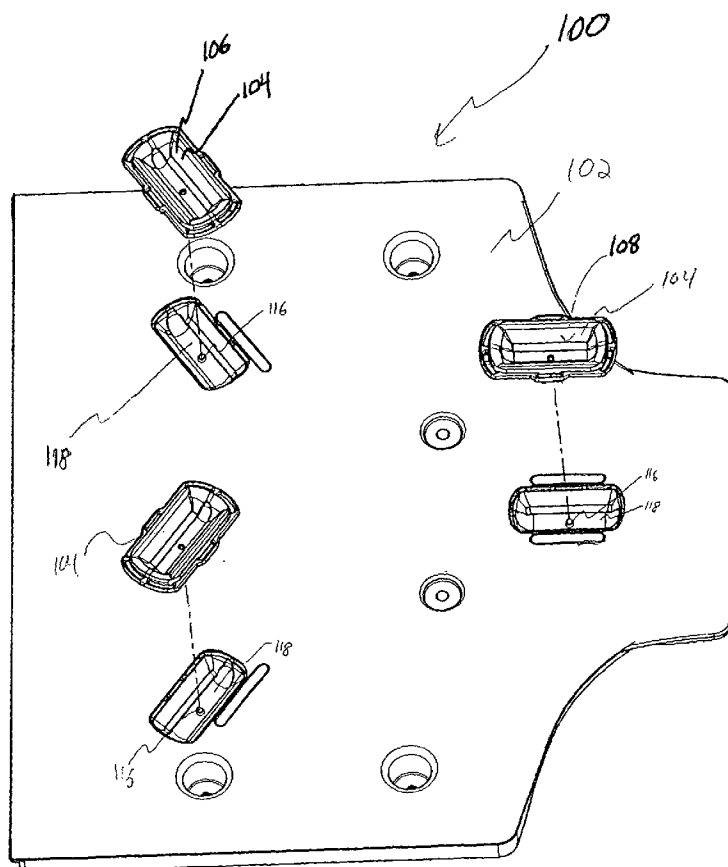
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(54) Title: COMPOSITE KINEMATIC COUPLING



(57) Abstract: The kinematic coupling of the present invention may comprise a wafer carrier base plate (100) comprising a first material, and a mounting plate (102) and multiple contact components (104). The mounting plate (102) has multiple recesses (118) corresponding to the number of contacts (104), each recess (118) provided with a protrusion (116) for engaging the bore of a respective contact component (104). The contact component (104) comprises a second material having a lower coefficient of friction than the first material. The contact component (104) may comprise an interior surface (108) with a contact surface (106) that converges as the interior surface (108) deepens. The contact component (104) may be provided to the base plate (100) as part of an over-molding, snap-in-place, staking, ultrasonic weld, or adhesive operation and held in place by mechanical interlocking.

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